



## Material Declaration Datasheet Restriction on Hazardous Substances (RoHS) Compliance

Manufacturer: Intel Corporation  
Equipment type: CPU Board  
Product Family Code: **DZ68DB**

Date: 04 April 2011  
Product: Lead-free Second Level Interconnect (SLI)

### RoHS Definitions:

Quantity limit of 0.1% by mass (1,000 ppm) for: Lead (Pb); Mercury; Hexavalent Chromium; Polybrominated Biphenyls (PBB); Polybrominated Diphenyl Ethers (PBDE). Quantity limit of 0.010% by mass (100 ppm) for Cadmium.

Intel understands RoHS compliance requires Lead and other materials banned in RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU, or (2) an approved or pending exemption applies. Note - RoHS implementation details are subject to change.

### RoHS Declaration:

This product is RoHS directive compliant but does contain Lead, a RoHS restricted substance per the definitions above. This product uses the following applicable RoHS technology exemptions: 5, 7a, 7c

This product has been verified to be in conformance with EU directive 2002/95/EC as currently understood. To the best of our knowledge the information contained in this declaration is true and correct.

### Level A Materials and Substances:

Materials from Annex A of the EIA/EICTA/JGPSSI Material Composition Declaration Guide are not contained in this product in quantities above the threshold level for these materials, nor intentionally added to this product.

This product does contain Lead or Lead compounds in discreet component parts above the homogenous material threshold level of 1,000 ppm per the RoHS exemptions above.

### Level B Materials and Substances:

This product does contain materials listed in Annex B of the EIA/EICTA/JGPSSI Material Composition Declaration Guide above the threshold level of 1,000 ppm as listed below.

Lead/Lead Compounds, Antimony/Antimony Compounds, Arsenic/Arsenic Compounds, Bismuth/Bismuth Compounds, Brominated Flame Retardants (other than PBBs or PBDEs), Nickel (external applications only).

### COMMENTS

1. The data reported for Level A and B materials and substances are based on analytical testing of a representative sample product. Individual test results may vary due to differences in production and/or sensitivities of analytical testing methods. Data shown reflect analytical testing intended to validate Intel's RoHS compliance systems. Intel's certification of RoHS compliance at the homogenous material level is based on Supplier Declarations of Conformance.
2. This declaration is based on the product specified, with all product skus of this product eligible to be covered by this declaration.
3. Material concentration data in parts per million (ppm) is representative of all product skus within the product family.
4. Material mass can be estimated by multiplying concentration (in ppm) by product weight.
5. The remainder of this product consists of non-reportable metals (i.e., copper, iron, tin), epoxy resin and other non-metal materials.

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